

# Fair-Rite P/N 2508053017Y3

## Y Chip Bead Material Grade

## Nominal Chemical Composition

<i><b>Ferrite -Compound</b></i>	<i><b>CAS Number</b></i>	<i><b>wt %</b></i>	Wt of core (g)= <b>0.008</b>	
Fe2O3	1309-37-1	65	0.0052	Compound Weight (g) Breakdown of Y Chip Bead Material Grade
ZnO	1314-13-2	17	0.0014	
NiO	1313-99-1	9	0.0007	
CuO	1317-38-0	6	0.0005	
MnO	1344-43-0	3	0.0002	

<i><b>Termination Plating - Elements</b></i>	<i><b>CAS Number</b></i>	<i><b>wt %</b></i>	Wt of termination (g)= <b>0.002</b>	
Sn	7440-31-5	14.3	0.000286	Element Weight (g) Breakdown of Pb- Free Termination Plating
Ni	7440-02-0	6.9	0.000138	
Ag	7440-22-4	78.8	0.001576	

### Supporting notes:

- P/N 2508053017Y3 consists of:  
a core Y Chip Bead Material Grade  
b Termination Plating SnNiAg
- Moisture Sensitivity Level (MSL)= 1
- Max Reflow Temp= 260 degC
- Max Time at Max Reflow Temp= 40 sec
- RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
- RoHS Conversion Date= 1/1/2005
- RoHS Compliance Marking is Contained on Shipping Labels

## Calculated Maximum Levels of RoHS Restricted Substances Present in Y Chip Bead Material Grade

<i><b>Impurity Substance</b></i>	<i><b>RoHS Threshold (ppm):</b></i>	<i><b>ppm</b></i>	Wt of core (g)= <b>0.008</b>	
Cr+6	1000	ND	ND	RoHS Impurity Substance Weight (g) Breakdown of Y Chip Bead Material Grade
Cd	100	ND	ND	
Hg	1000	ND	ND	
Pb	1000	ND	ND	
PBB	1000	ND	ND	
PBDE	1000	ND	ND	
Bis(2-Ethylhexyl) phthalate (DEHP)	1000	ND	ND	
Benzyl butyl phthalate (BBP)	1000	ND	ND	
Dibutyl phthalate (DBP)	1000	ND	ND	
Diisobutyl phthalate (DIBP)	1000	ND	ND	